



LTEM NO.: MC-312D-C

(L7.90mm × W8.94mm × H3.20mm CONNECTORS)



邀您使用(微信)小程序  
硕方电子开关&连接器选型手册  
手机扫码即可进入...

### Technical parameter

表面 SMT+DIP

侧向导入 LATERAL

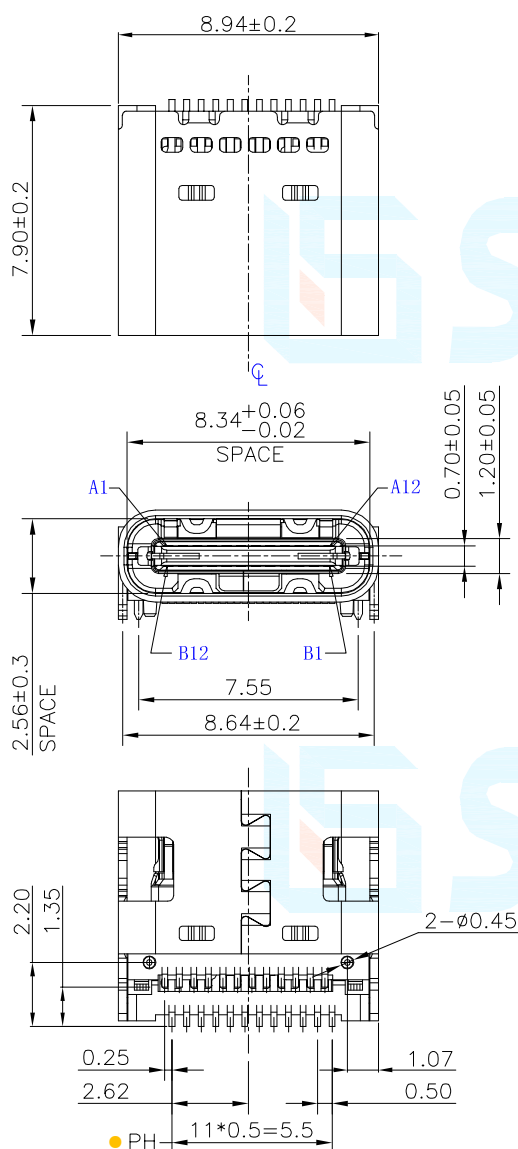
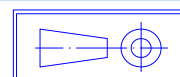
精密部品 NICETY

可靠 STABILIZE

適合環保 RoHS

| PROJECT               | LEVEL                      | A[better product]           | B[average product]         |
|-----------------------|----------------------------|-----------------------------|----------------------------|
|                       | Contact Rating             | 5.0A, 12V DC                |                            |
| Electrical Properties | Initial Contact Resistance | 30mΩ max.                   | 50mΩ max.                  |
|                       | Insulation Resistance      | 100MΩ min.500V DC           | Skey/PD: 100MΩ min.300V DC |
|                       | Withstand Voltage          | 500V AC for 1 minute        | 350 V AC for 1 minut       |
| Durable Performance   | There No Load              | 10,000 Cycles               | 8,000 Cycles               |
|                       | Rated Load                 | 8,500 Cycles                | 6,500 Cycles               |
|                       | Storage temp.              | -35℃~+75℃(Operating Temp: ) |                            |

Unit:mm



### Material declaration

| No. | NAME                | MATERIAL              | DESCRIPTION                                                                                |
|-----|---------------------|-----------------------|--------------------------------------------------------------------------------------------|
| ① A | TERMINAL<br>接触端子    | COPPER ALLOY<br>【G/F】 | 2.0 μm Ni PLATED OVERALL;<br>0.25 μm Au PLATED CONTACT AREA;<br>GOLD FLASH ON SOLDER AREA. |
| ② B | HOUSING 基座          | THERMOPLASTIC         | UL 94V-0,COLOR:BLACK;                                                                      |
| ③ C | SHIELDING PLATE 屏蔽壳 | STAINLESS STEE        | 【G/F】 0.25 μm Ni PLATED OVERALL;                                                           |
| ④ D | SHELL 外壳            | STAINLESS STEE        | 【G/F】 0.25 μm Ni PLATED OVERALL;                                                           |
| ⑤ E | GND RING 接地件        | STAINLESS STEE        | STAINLESS STEEL;                                                                           |

## Operating Force

Inward

5.0~8.0N. (1N.=100gram-force)

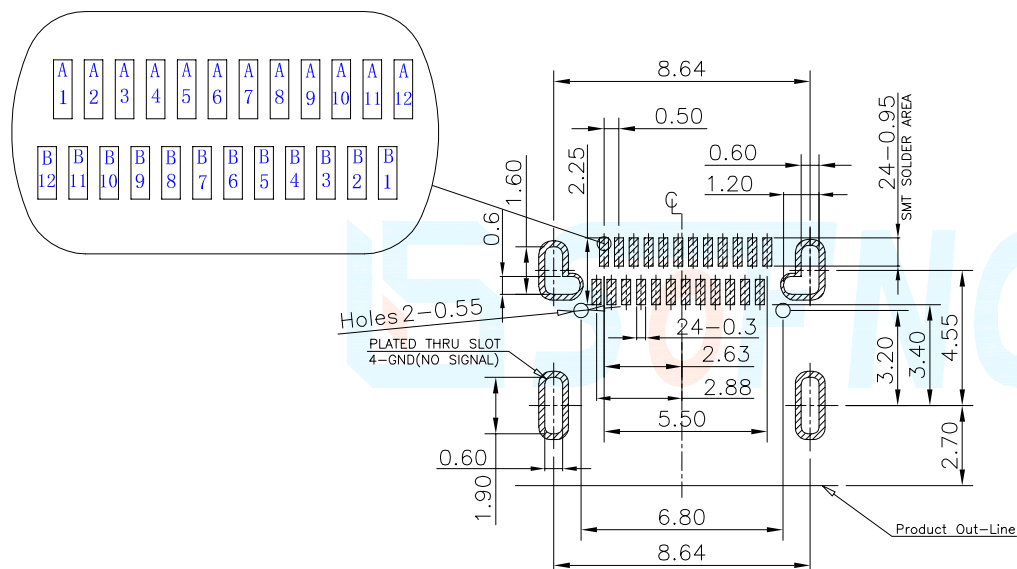
Exiting

5.0~8.0N. (1N.=100gram-force)

## Solder-ability (Max.)

IR Reflow: 255°C, 5sec.

Manual: 350°C, 3sec.

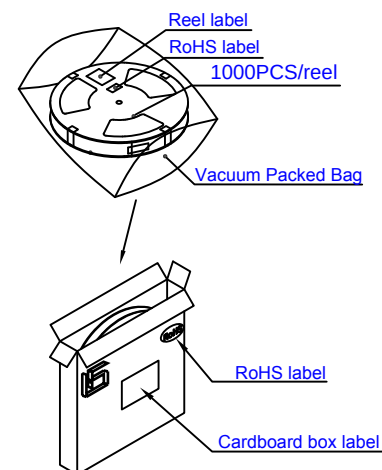


| DECIMALS    | ANGLES       |
|-------------|--------------|
| .X :±0.25   | X.° :±1.5°   |
| .XX :±0.15  | XX.° :±1.0°  |
| .XXX :±0.10 | XXX.° :±0.5° |

## Pin Definition



| PIN | Signal NAME | Description                                               | PIN | Signal NAME | Description                                               |
|-----|-------------|-----------------------------------------------------------|-----|-------------|-----------------------------------------------------------|
| A 1 | GND         | Ground return                                             | B12 | GND         | Ground return                                             |
| A 2 | SSTXp1      | Positive half of first SuperSpeed TX differential pair    | B11 | SSRXp1      | Positive half of second SuperSpeed RX differential pair   |
| A 3 | SSTXn1      | Negative half of first SuperSpeed TX differential pair    | B10 | SSRXn1      | Negative half of second SuperSpeed RX differential pair   |
| A 4 | V BUS       | Bus Power                                                 | B 9 | V BUS       | Bus Power                                                 |
| A 5 | CC1         | Configuration Channel                                     | B 8 | SBU2        | Sideband Use (SBU)                                        |
| A 6 | Dp1         | Positive half of the USB 2.0 differential pair-Position 1 | B 7 | Dn2         | Negative half of the USB 2.0 differential pair-Position 2 |
| A 7 | Dn1         | Negative half of the USB 2.0 differential pair-Position 1 | B 6 | Dp2         | Positive half of the USB 2.0 differential pair-Position 2 |
| A 8 | SBU1        | Sideband Use (SBU)                                        | B 5 | CC2         | Configuration Channel                                     |
| A 9 | V BUS       | Bus Power                                                 | B 4 | V BUS       | Bus Power                                                 |
| A10 | SSRXn2      | Negative half of second SuperSpeed RX differential pair   | B 3 | SSTXn2      | Negative half of first SuperSpeed TX differential pair2   |
| A11 | SSRXp2      | Positive half of second SuperSpeed RX differential pair   | B 2 | SSTXp2      | Positive half of first SuperSpeed TX differential pair2   |
| A12 | GND         | Ground return                                             | B 1 | GND         | Ground return                                             |



本品不屬於危害性廢棄物,須丟棄時可以委託  
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